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**Diamond**(10) **Pub. No.: US 2022/0377888 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **TRANSPARENT PACKAGE FOR USE WITH  
PRINTED CIRCUIT BOARDS****H05K 1/03** (2006.01)**H05K 1/09** (2006.01)(71) Applicant: **Honeywell Federal Manufacturing &  
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**ABSTRACT**(21) Appl. No.: **17/579,974**(22) Filed: **Jan. 20, 2022****Related U.S. Application Data**(60) Provisional application No. 63/191,194, filed on May  
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A blank package for mimicking an electronic component package comprises a body and a plurality of conductive pads. The body is formed from generally transparent electrically insulating material and has a top surface, a bottom surface, and a plurality of side surfaces. The bottom surface has a shape and dimensions that are similar to a bottom surface of the electronic component package. The conductive pads are formed from electrically conductive material and attached to the body, with each conductive pad corresponding to a successive one of the conductive pads of the electronic component package. Each conductive pad has features that are similar to features of the corresponding conductive pad of the electronic component package.

